

REV	ECO	DESCRIPTION	DRFT	CHKD
△		原始版本		

NOTES:

MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER(UL94V-0).
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE $\varnothing 0.46\text{mm}$ (C5100).
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.SHIELD: COPPER ALLOY 0.20mm THICKNESS PLATING NI.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.
- 5.DIELECTRIC WITHSTANDING
RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1.STORAGE : -40°C TO $+85^{\circ}\text{C}$.

2. OPERATION : 0°C TO 70°C .

MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.

PART NUMBER:

△58-0310810XX2X

58 SERIES
PCB JACK
(58系列PCB接口)

SHIELD (屏蔽壳) :

1-W/O SHIELD (非屏)

2-HALF SHIELD (半包)

3-FULL SHIELD (全包)

PORTS (插口) :

1-1X1 (一口) . 2-1X2 (二口)

4-1X4 (四口) . 5-1X5 (五口)

6-1X6 (六口) . 8-1X8 (八口)

POSITIONS (金针位置) :

4-4POSITIONS (4P)

6-6POSITIONS (6P)

8-8POSITIONS (8P)

0-10POSITIONS (10P)

CONTACTS (金针根数) :

2-2CONTACTS (2C) . 4-4CONTACTS (4C)

6-6CONTACTS (6C) . 8-8CONTACTS (8C)

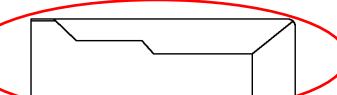
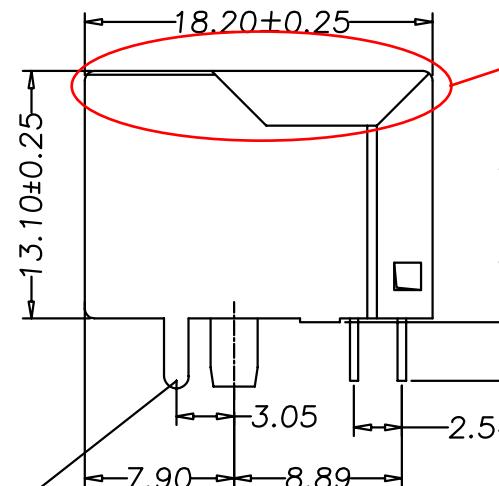
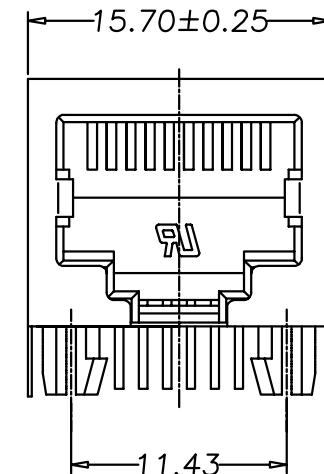
0-10CONTACTS (10C)

PEG/TAB (边定位铁脚) :

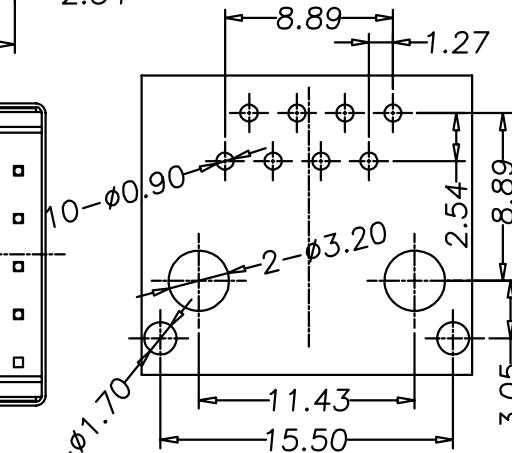
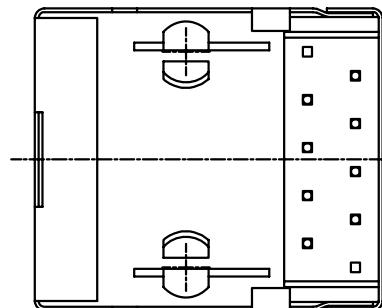
0-W/O PEG (无铁脚) . 1-FRONT PEG 3.05 (前脚3.05)

2-FRONT PEG3.68 (前脚3.68) . 3-FRONT PEG4.57 (前脚4.57)

4-BACK PEG3.05 (后脚3.05)



产品铁壳的形状是
上图的形状



PC Board Layout

DETACHED LISTS	MM (INCH)	设计 yuanmin	日期 08.10.24	系列	名称
	一 最 公 差 栏	审核 zhangwei	日期 08.10.25		
MM .0 ±0.20 .00 ±0.15 .000 ±0.075	±	批准 zhangke	日期 08.10.25	系列	5803-10P8C
	±	材料:			
角度 ± 0.01°	数量:			图号	A4
	表面处理:				
第三 角 视 图	比例: 1:1	不 按 比 例	关 X 頁 第 Y 頁	A4	A